



Material Content Data Sheet



Sales Product Name		IPU60R1K5CE		Issued		27. September 2017		
MA#		MA001507200						
Package		PG-TO251-3-345		Weight*		384.99 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.513	0.39	0.39	3931	3931
leadframe	non noble metal	iron	7439-89-6	0.209	0.05		542	
	inorganic material	phosphorus	7723-14-0	0.063	0.02		162	
	non noble metal	copper	7440-50-8	208.238	54.09	54.16	540896	541600
wire	non noble metal	aluminium	7429-90-5	4.187	1.09	1.09	10876	10876
encapsulation	organic material	carbon black	1333-86-4	0.685	0.18		1780	
	plastics	epoxy resin	-	18.508	4.81		48073	
	inorganic material	silicondioxide	60676-86-0	117.900	30.62	35.61	306246	356099
leadfinish	non noble metal	tin	7440-31-5	7.055	1.83	1.83	18325	18325
solder	noble metal	silver	7440-22-4	0.043	0.01		112	
	non noble metal	tin	7440-31-5	0.034	0.01		89	
	non noble metal	lead	7439-92-1	1.640	0.43	0.45	4261	4462
heatspreader	non noble metal	iron	7439-89-6	0.025	0.01		65	
	inorganic material	phosphorus	7723-14-0	0.007	0.00		19	
	non noble metal	copper	7440-50-8	24.879	6.46	6.47	64623	64707
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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